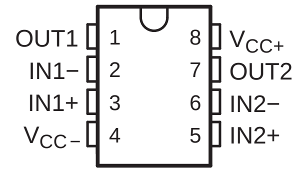
## FEATURES

- **Dual-Supply Operation . . . ±5 V to ±18 V**
- **Low Noise Voltage . . . 4.5 nV/√Hz**
- **Low Input Offset Voltage . . . 0.15 mV**
- **Low Total Harmonic Distortion . . . 0.002%**
- **High Slew Rate . . . 7 V/μs**
- **High-Gain Bandwidth Product . . . 16 MHz**
- **High Open-Loop AC Gain . . . 800 at 20 kHz**
- **Large Output-Voltage Swing . . . 14.1 V to –14.6 V**
- **Excellent Gain and Phase Margins**

**D (SOIC), DGK (MSOP), OR P (PDIP) PACKAGE**
**(TOP VIEW)**




## DESCRIPTION/ORDERING INFORMATION

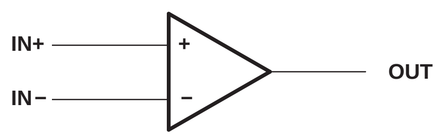
The MC33078 is a bipolar dual operational amplifier with high-performance specifications for use in quality audio and data-signal applications. This device operates over a wide range of single- and dual-supply voltages and offers low noise, high-gain bandwidth, and high slew rate. Additional features include low total harmonic distortion, excellent phase and gain margins, large output voltage swing with no deadband crossover distortion, and symmetrical sink/source performance.

### ORDERING INFORMATION

| $T_A$ | PACKAGE(1) | | ORDERABLE PART NUMBER | TOP-SIDE MARKING(2) |
|---|---|---|---|---|
| –40°C to 85°C | PDIP – P | Tube of 50 | MC33078P | MC33078P |
| | SOIC – D | Tube of 75 | MC33078D | M33078 |
| | | Reel of 2500 | MC33078DR | |
| | VSSOP/MSOP – DGK | Reel of 2500 | MC33078DGKR | MY_ |
| | | Reel of 250 | MC33078DGKT | |

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
(2) DGK: The actual top-side marking has one additional character that designates the assembly/test site.

### SYMBOL (EACH AMPLIFIER)



## Absolute Maximum Ratings[1]

over operating free-air temperature range (unless otherwise noted)

| | | | MIN | MAX | UNIT |
|---|---|---|---|---|---|
| $V_{CC+}$ | Supply voltage[2] | | | 18 | V |
| $V_{CC-}$ | Supply voltage[2] | | | –18 | V |
| $V_{CC+} – V_{CC-}$ | Supply voltage | | | 36 | V |
| | Input voltage, either input[2][3] | | | $V_{CC+}$ or $V_{CC-}$ | V |
| | Input current[4] | | | ±10 | mA |
| | Duration of output short circuit[5] | | | Unlimited | |
| $\theta_{JA}$ | Package thermal impedance, junction to free air[6][7] | D package | | 97 | °C/W |
| | | DGK package | | 172 | |
| | | P package | | 85 | |
| $T_J$ | Operating virtual junction temperature | | | 150 | °C |
| $T_{stg}$ | Storage temperature range | | –65 | 150 | °C |

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values, except differential voltages, are with respect to the midpoint between $V_{CC+}$ and $V_{CC-}$.
(3) The magnitude of the input voltage must never exceed the magnitude of the supply voltage.
(4) Excessive input current will flow if a differential input voltage in excess of approximately 0.6 V is applied between the inputs, unless some limiting resistance is used.
(5) The output may be shorted to ground or either power supply. Temperature and/or supply voltages must be limited to ensure the maximum dissipation rating is not exceeded.
(6) Maximum power dissipation is a function of $T_J$(max), $\theta_{JA}$, and $T_A$. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) – T_A)/\theta_{JA}$. Operating at the absolute maximum $T_J$ of 150°C can affect reliability.
(7) The package thermal impedance is calculated in accordance with JESD 51-7.

## Recommended Operating Conditions

| | | MIN | MAX | UNIT |
|---|---|---|---|---|
| $V_{CC-}$ | Supply voltage | –5 | –18 | V |
| $V_{CC+}$ | | 5 | 18 | |
| $T_A$ | Operating free-air temperature range | –40 | 85 | °C |

## Electrical Characteristics

$V_{CC-}$ = –15 V, $V_{CC+}$ = 15 V, $T_A$ = 25°C (unless otherwise noted)

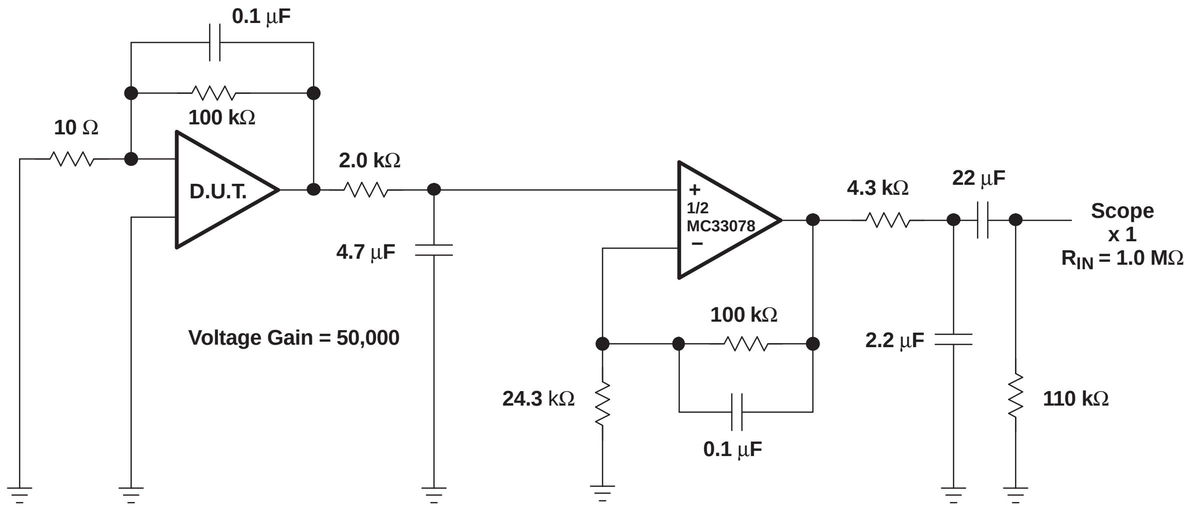
| PARAMETER | | TEST CONDITIONS | | | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|---|---|
| $V_{IO}$ | Input offset voltage | $V_O$ = 0, $R_S$ = 10 Ω, $V_{CM}$ = 0 | | $T_A$ = 25°C | | 0.15 | 2 | mV |
| | | | | $T_A$ = –40°C to 85°C | | | 3 | |
| $\alpha V_{IO}$ | Input offset voltage temperature coefficient | $V_O$ = 0, $R_S$ = 10 Ω, $V_{CM}$ = 0 | | $T_A$ = –40°C to 85°C | | 2 | | µV/°C |
| $I_{IB}$ | Input bias current | $V_O$ = 0, $V_{CM}$ = 0 | | $T_A$ = 25°C | | 300 | 750 | nA |
| | | | | $T_A$ = –40°C to 85°C | | | 800 | |
| $I_{IO}$ | Input offset current | $V_O$ = 0, $V_{CM}$ = 0 | | $T_A$ = 25°C | | 25 | 150 | nA |
| | | | | $T_A$ = –40°C to 85°C | | | 175 | |
| $V_{ICR}$ | Common-mode input voltage range | $\Delta V_{IO}$ = 5 mV, $V_O$ = 0 | | | ±13 | ±14 | | V |
| $A_{VD}$ | Large-signal differential voltage amplification | $R_L \geq$ 2 kΩ, $V_O$ = ±10 V | | $T_A$ = 25°C | 90 | 110 | | dB |
| | | | | $T_A$ = –40°C to 85°C | 85 | | | |
| $V_{OM}$ | Maximum output voltage swing | $V_{ID}$ = ±1 V | $R_L$ = 600 Ω | $V_{OM+}$ | | 10.7 | | V |
| | | | | $V_{OM-}$ | | –11.9 | | |
| | | | $R_L$ = 2k Ω | $V_{OM+}$ | 13.2 | 13.8 | | |
| | | | | $V_{OM-}$ | –13.2 | –13.7 | | |
| | | | $R_L$ = 10k Ω | $V_{OM+}$ | 13.5 | 14.1 | | |
| | | | | $V_{OM-}$ | –14 | –14.6 | | |
| CMMR | Common-mode rejection ratio | $V_{IN}$ = ±13 V | | | 80 | 100 | | dB |
| $k_{SVR}$ (1) | Supply-voltage rejection ratio | $V_{CC+}$ = 5 V to 15 V, $V_{CC-}$ = –5 V to –15 V | | | 80 | 105 | | dB |
| $I_{OS}$ | Output short-circuit current | $\|V_{ID}\|$ = 1 V, Output to GND | | Source current | 15 | 29 | | mA |
| | | | | Sink current | –20 | –37 | | |
| $I_{CC}$ | Supply current (per channel) | $V_O$ = 0 | | $T_A$ = 25°C | | 2.05 | 2.5 | mA |
| | | | | $T_A$ = –40°C to 85°C | | | 2.75 | |

(1) Measured with $V_{CC\pm}$ differentially varied at the same time

## Operating Characteristics

$V_{CC-}$ = –15 V, $V_{CC+}$ = 15 V, $T_A$ = 25°C (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|---|
| SR | Slew rate at unity gain | $A_{VD}$ = 1, $V_{IN}$ = –10 V to 10 V, $R_L$ = 2 kΩ, $C_L$ = 100 pF | | 5 | 7 | | V/µs |
| GBW | Gain bandwidth product | f = 100 kHz | | 10 | 16 | | MHz |
| $B_1$ | Unity gain frequency | Open loop | | | 9 | | MHz |
| $G_m$ | Gain margin | $R_L$ = 2 kΩ | $C_L$ = 0 pF | | –11 | | dB |
| | | | $C_L$ = 100 pF | | –6 | | |
| $\Phi_m$ | Phase margin | $R_L$ = 2 kΩ | $C_L$ = 0 pF | | 55 | | deg |
| | | | $C_L$ = 100 pF | | 40 | | |
| | Amp-to-amp isolation | f = 20 Hz to 20 kHz | | | –120 | | dB |
| | Power bandwidth | $V_O$ = 27 $V_{(PP)}$, $R_L$ = 2 kΩ, THD ≤ 1% | | | 120 | | kHz |
| THD | Total harmonic distortion | $V_O$ = 3 $V_{rms}$, $A_{VD}$ = 1, $R_L$ = 2 kΩ, f = 20 Hz to 20 kHz | | | 0.002 | | % |
| $z_o$ | Open-loop output impedance | $V_O$ = 0, f = 9 MHz | | | 37 | | Ω |
| $r_{id}$ | Differential input resistance | $V_{CM}$ = 0 | | | 175 | | kΩ |
| $C_{id}$ | Differential input capacitance | $V_{CM}$ = 0 | | | 12 | | pF |
| $V_n$ | Equivalent input noise voltage | f = 1 kHz, $R_S$ = 100 Ω | | | 4.5 | | nV/√Hz |
| $I_n$ | Equivalent input noise current | f = 1 kHz | | | 0.5 | | pA/√Hz |

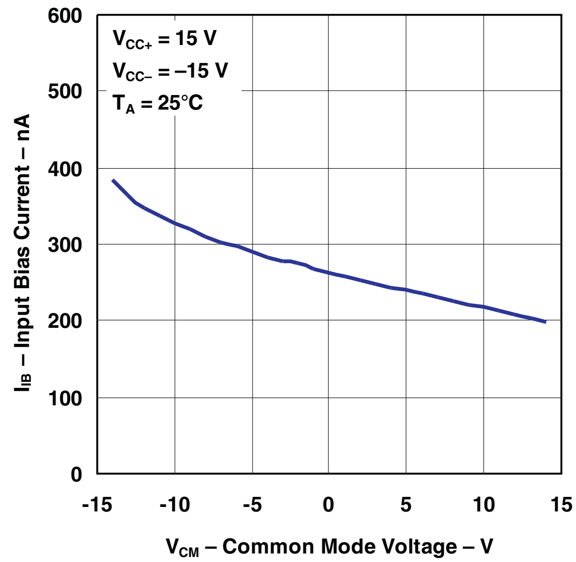



NOTE: All capacitors are non-polarized.

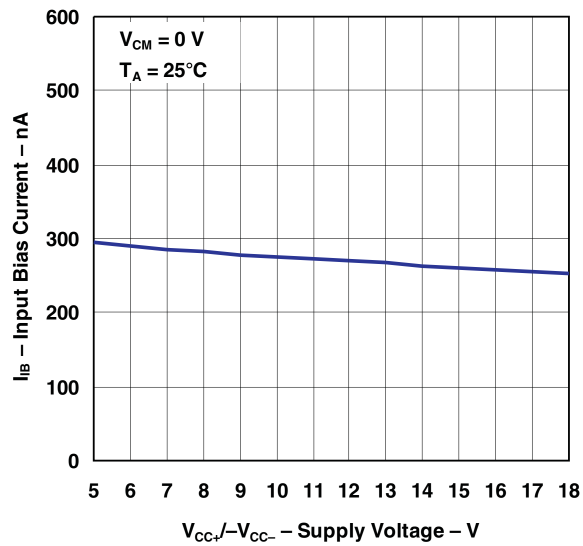
**Figure 1. Voltage Noise Test Circuit (0.1 Hz to 10 Hz)**

## TYPICAL CHARACTERISTICS

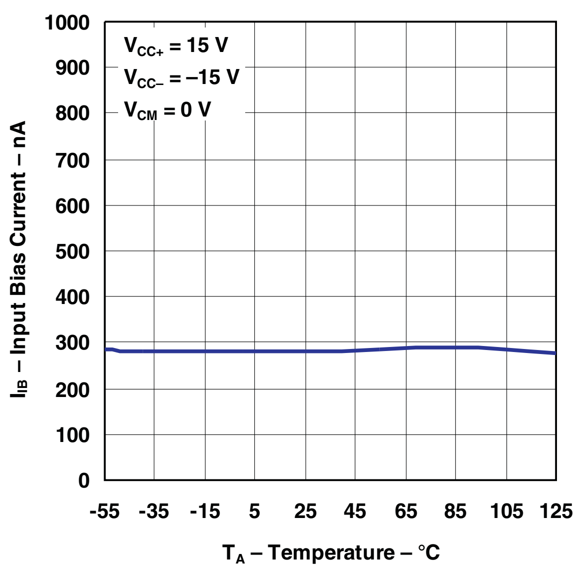
**INPUT BIAS CURRENT**
**vs**
**COMMON-MODE VOLTAGE**



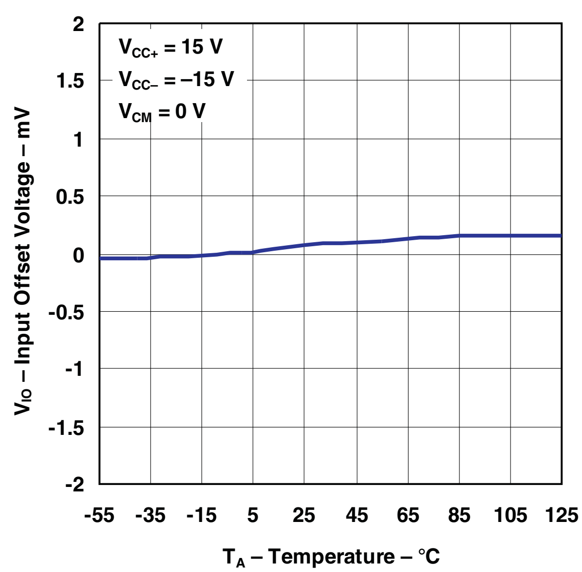

**INPUT BIAS CURRENT**
**vs**
**SUPPLY VOLTAGE**




**INPUT BIAS CURRENT**
**vs**
**TEMPERATURE**

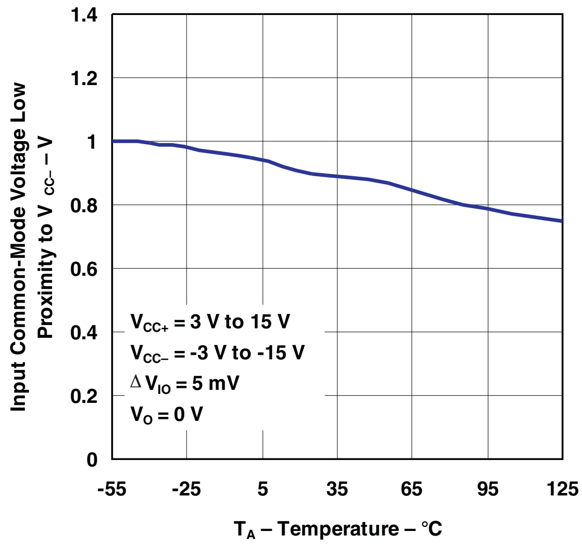



**INPUT OFFSET VOLTAGE**
**vs**
**TEMPERATURE**

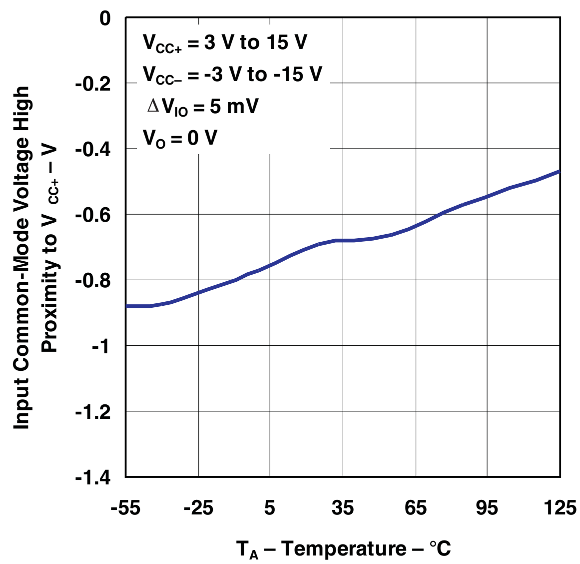


## TYPICAL CHARACTERISTICS (continued)

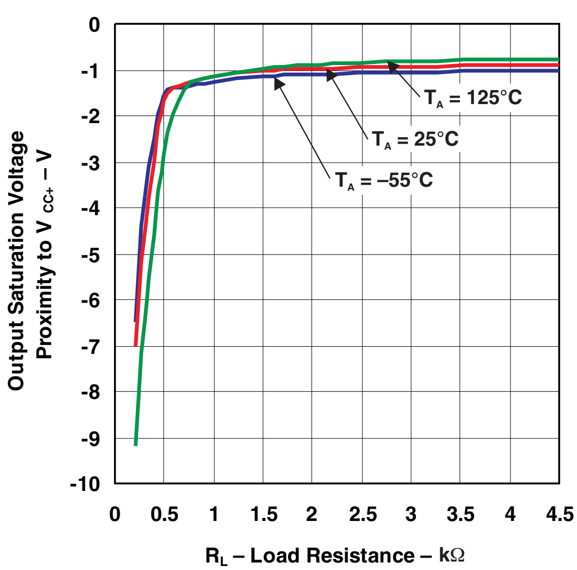
**INPUT COMMON-MODE VOLTAGE LOW PROXIMITY TO $V_{CC-}$ vs TEMPERATURE**



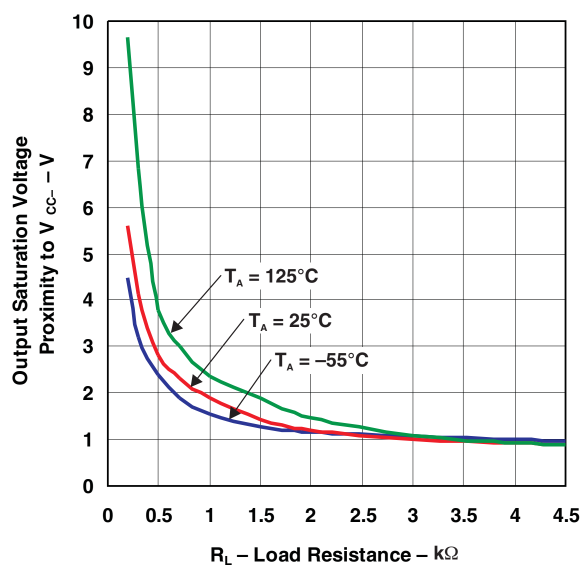

**INPUT COMMON-MODE VOLTAGE HIGH PROXIMITY TO $V_{CC+}$ vs TEMPERATURE**




**OUTPUT SATURATION VOLTAGE PROXIMITY TO $V_{CC+}$ vs LOAD RESISTANCE**

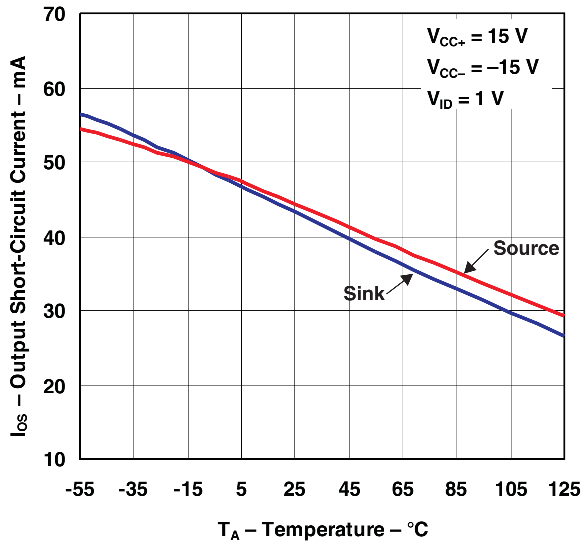



**OUTPUT SATURATION VOLTAGE PROXIMITY TO $V_{CC-}$ vs LOAD RESISTANCE**

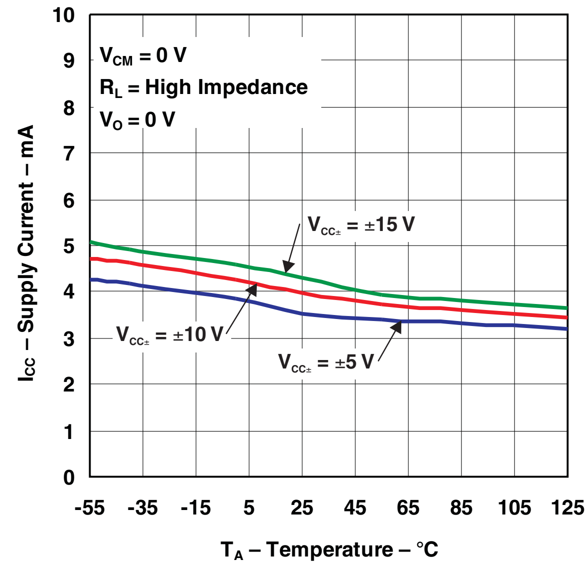


## TYPICAL CHARACTERISTICS (continued)

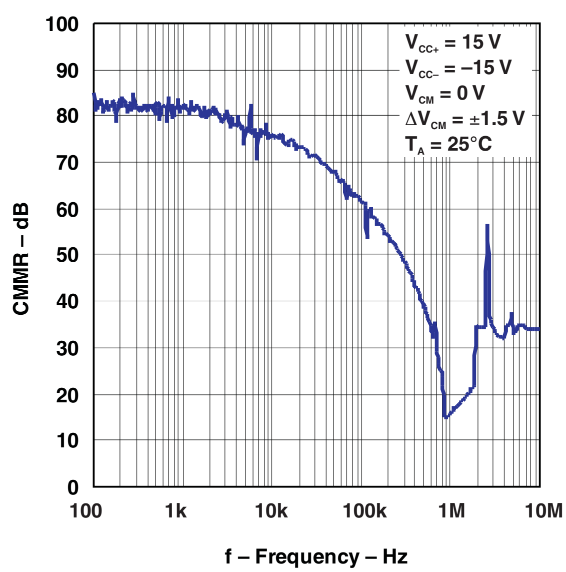
OUTPUT SHORT-CIRCUIT CURRENT
vs
TEMPERATURE



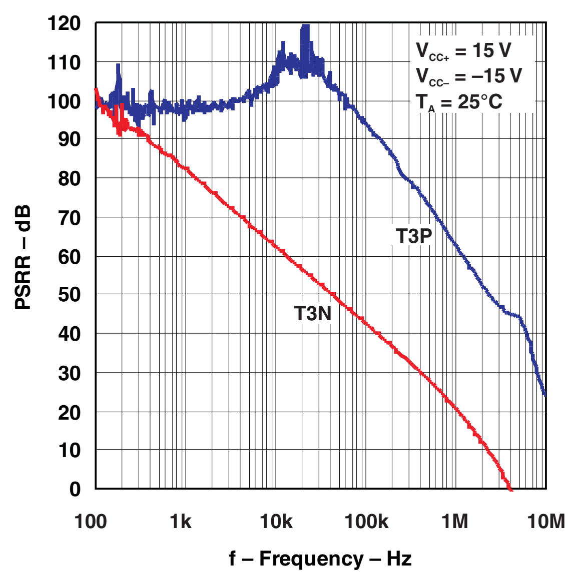

SUPPLY CURRENT
vs
TEMPERATURE




CMRR
vs
FREQUENCY

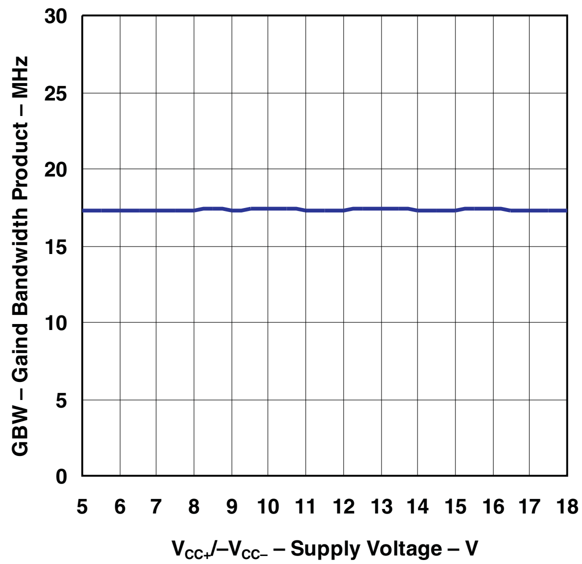



PSSR
vs
FREQUENCY

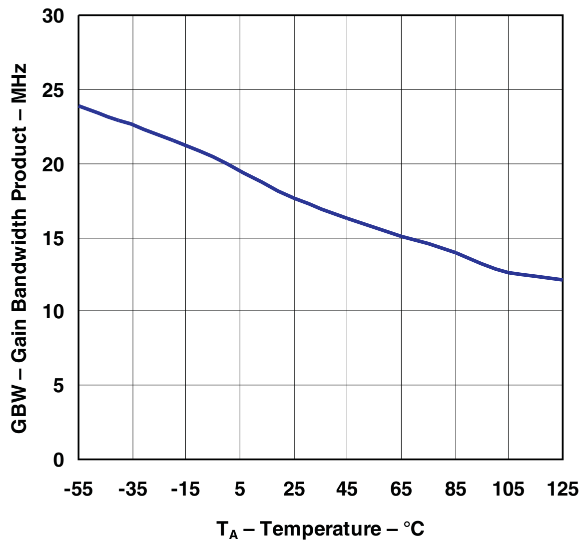


## TYPICAL CHARACTERISTICS (continued)

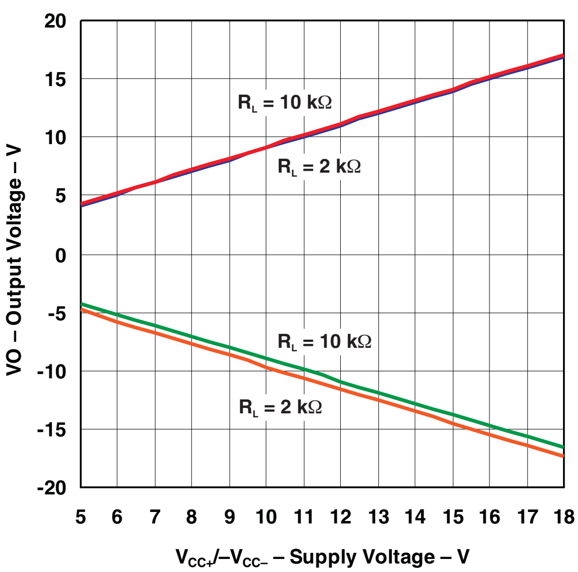
GAIN BANDWIDTH PRODUCT
vs
SUPPLY VOLTAGE



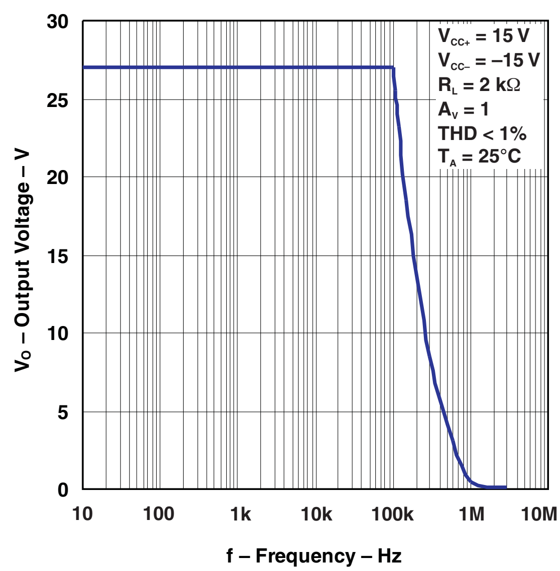

GAIN BANDWIDTH PRODUCT
vs
TEMPERATURE




OUTPUT VOLTAGE
vs
SUPPLY VOLTAGE

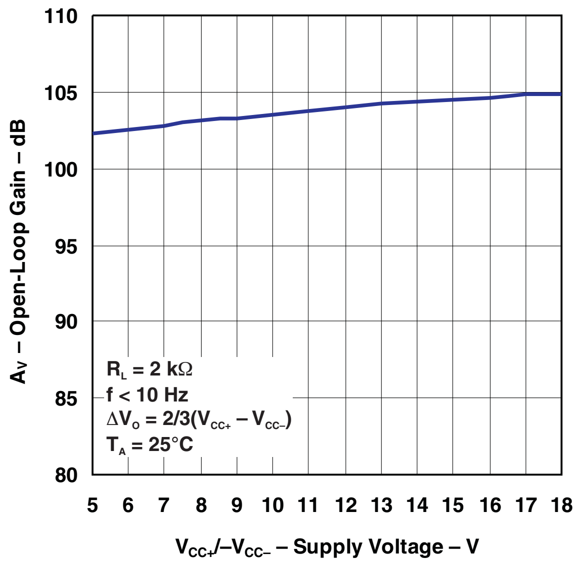



OUTPUT VOLTAGE
vs
FREQUENCY

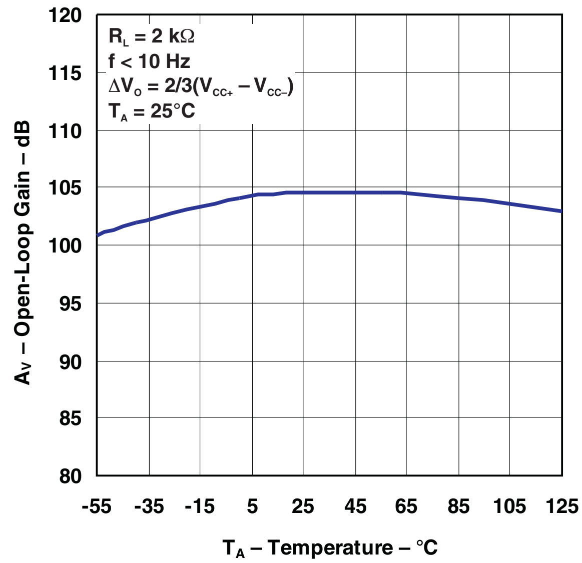


## TYPICAL CHARACTERISTICS (continued)

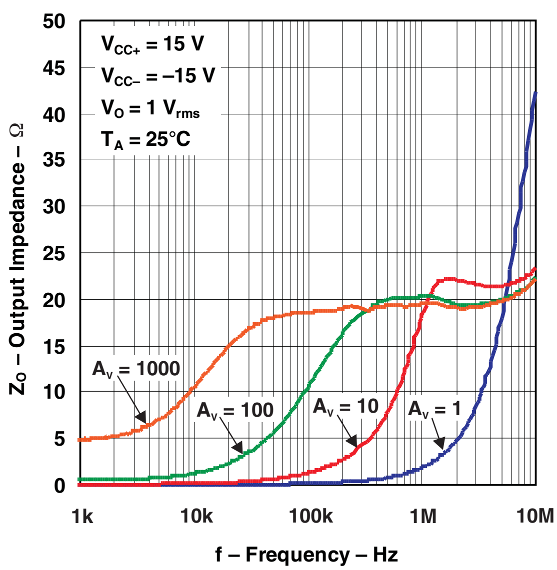
OPEN-LOOP GAIN
vs
SUPPLY VOLTAGE



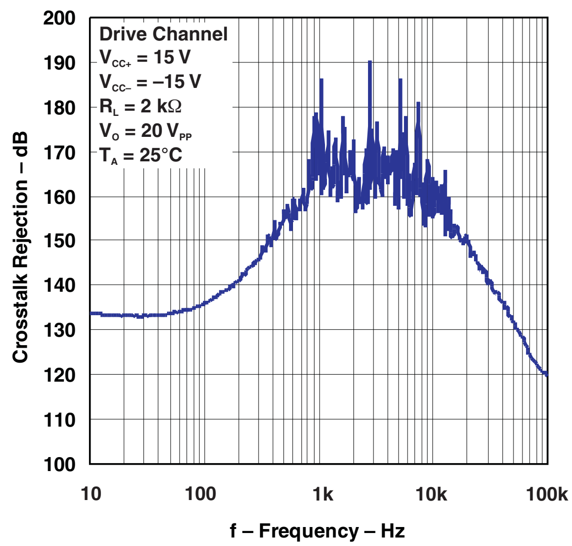

OPEN-LOOP GAIN
vs
TEMPERATURE



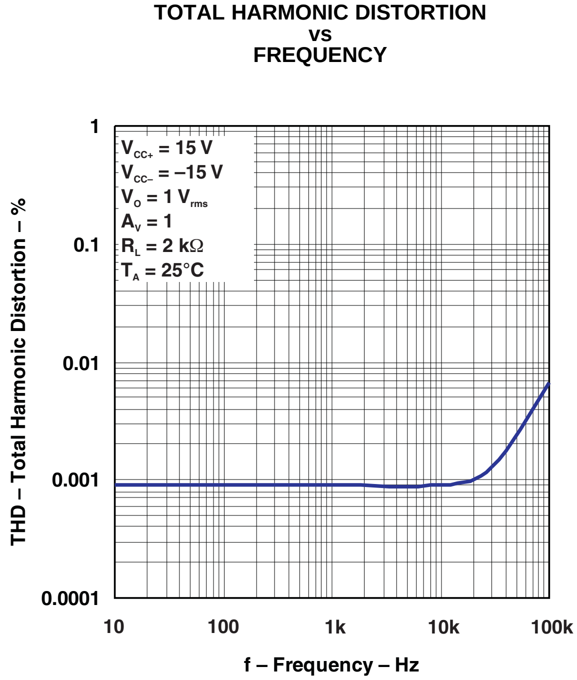

OUTPUT IMPEDANCE
vs
FREQUENCY

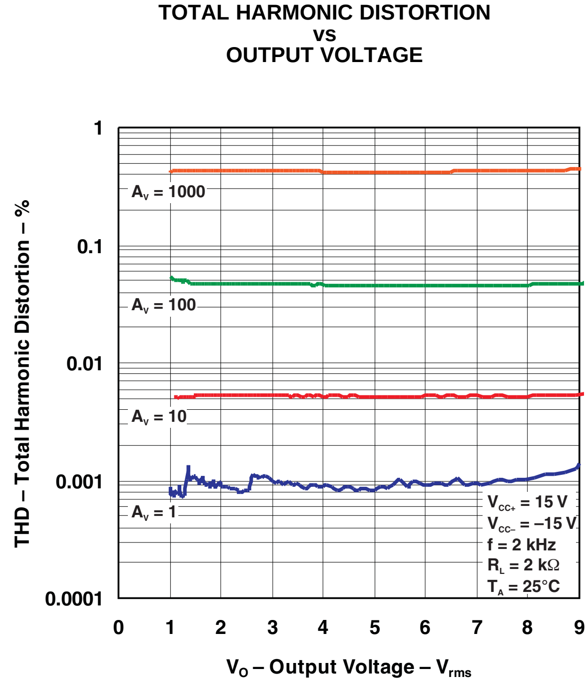


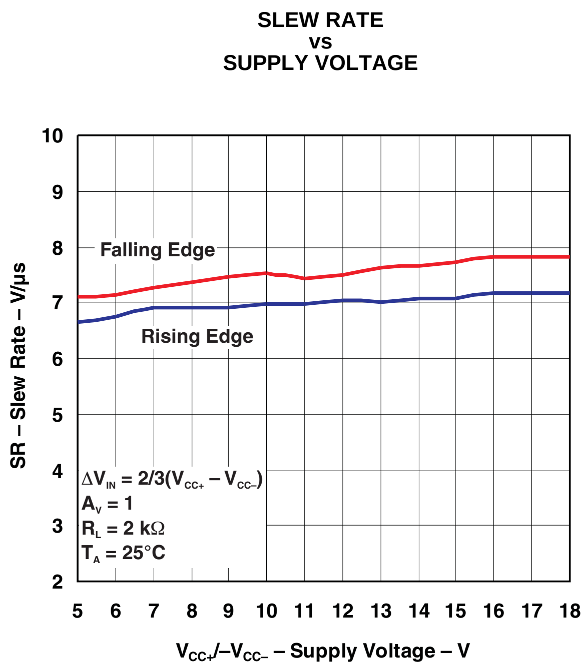

CROSSTALK REJECTION
vs
FREQUENCY

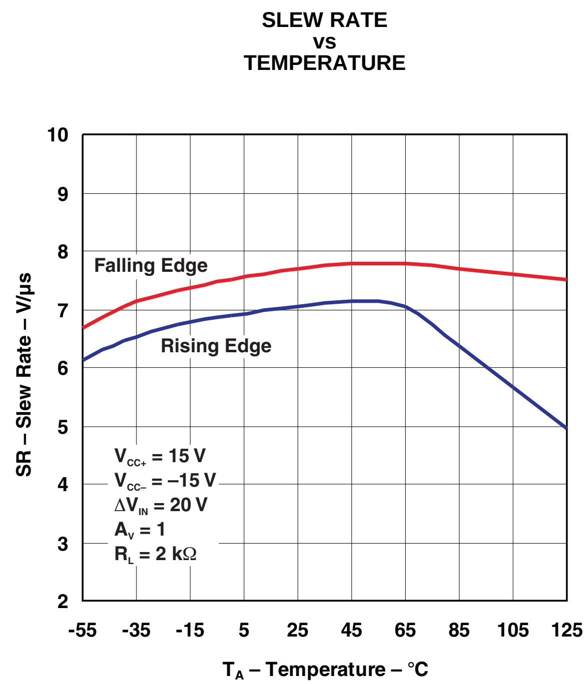


## TYPICAL CHARACTERISTICS (continued)



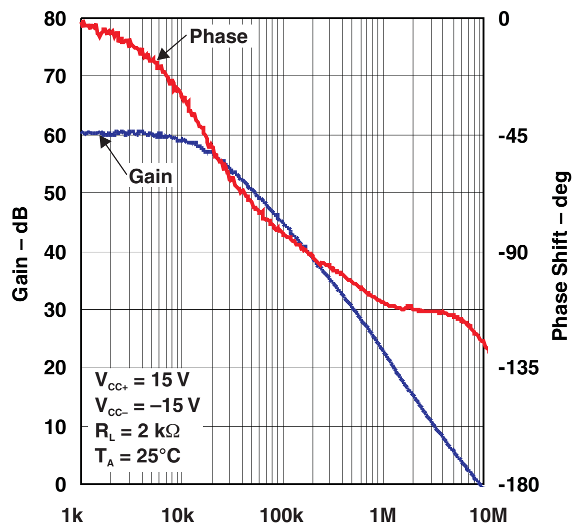



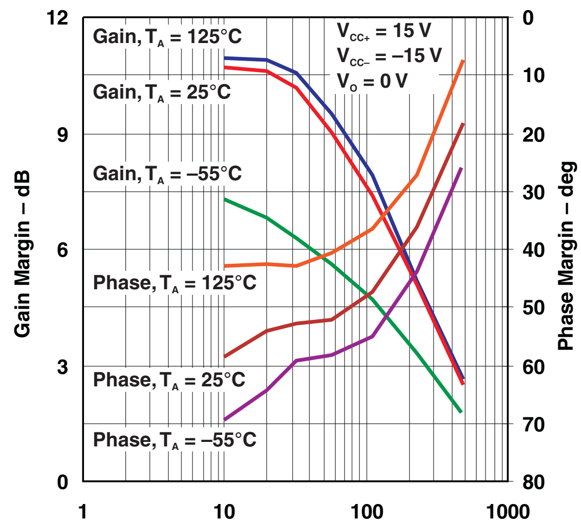



## TYPICAL CHARACTERISTICS (continued)

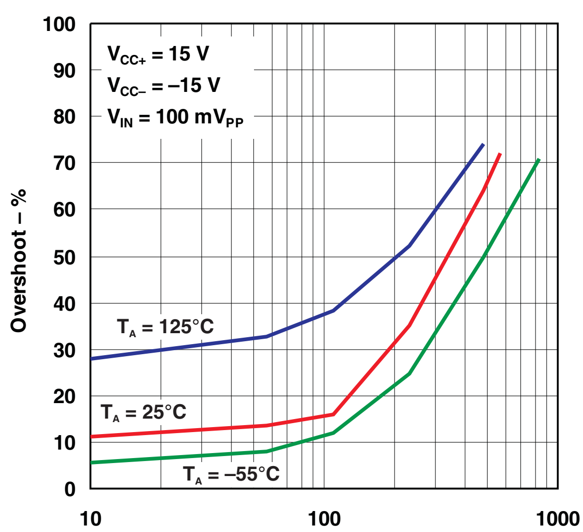
**GAIN AND PHASE vs FREQUENCY**



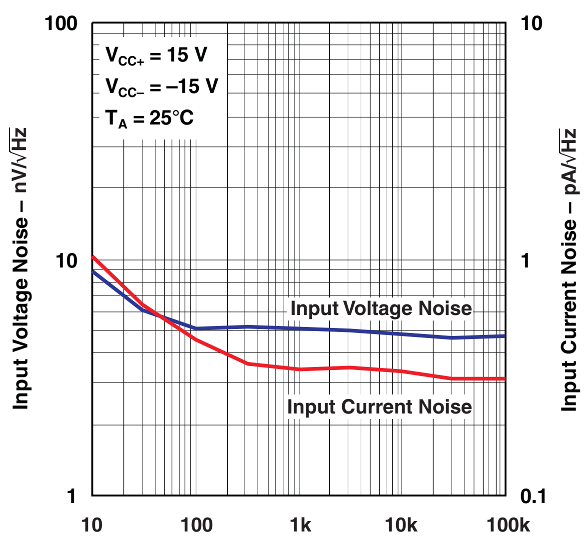

**GAIN AND PHASE MARGIN vs OUTPUT LOAD CAPACITANCE**




**OVERSHOOT vs OUTPUT LOAD CAPACITANCE**

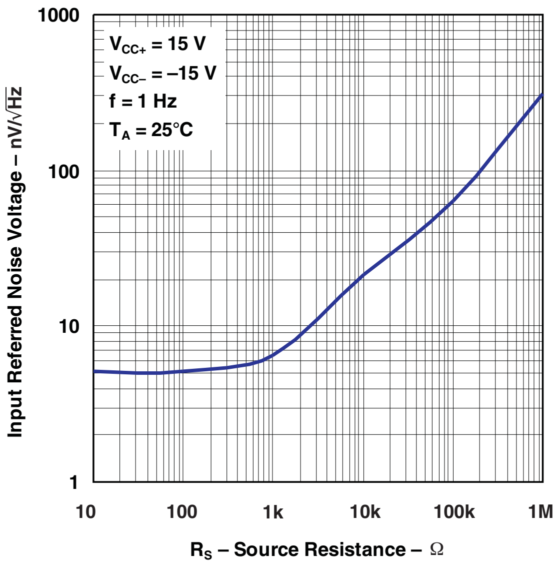



**INPUT VOLTAGE AND CURRENT NOISE vs FREQUENCY**

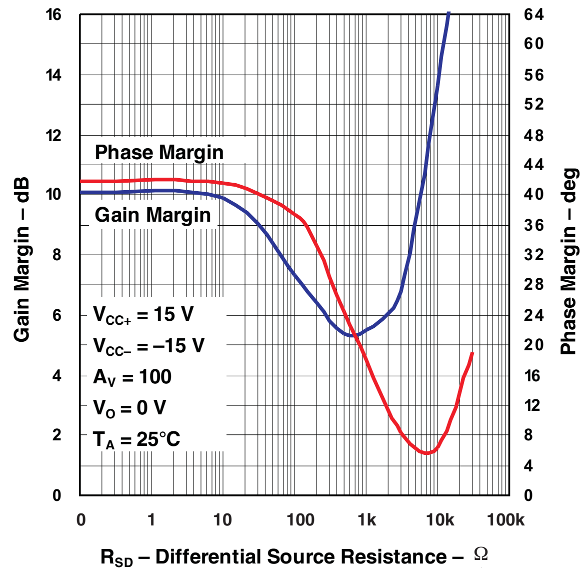


## TYPICAL CHARACTERISTICS (continued)

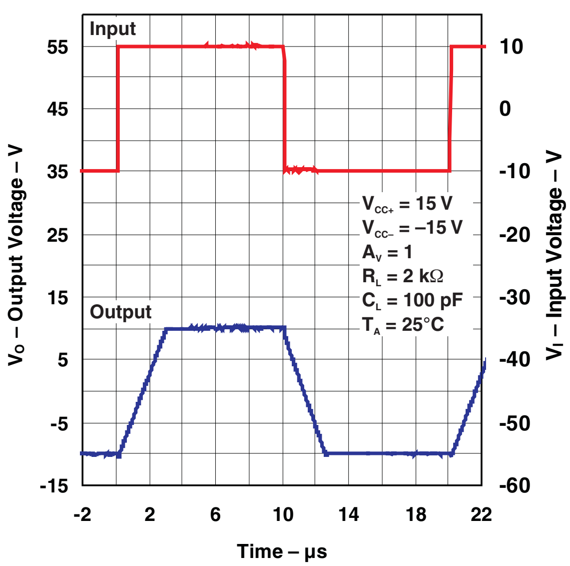
**INPUT REFERRED NOISE VOLTAGE vs SOURCE RESISTANCE**



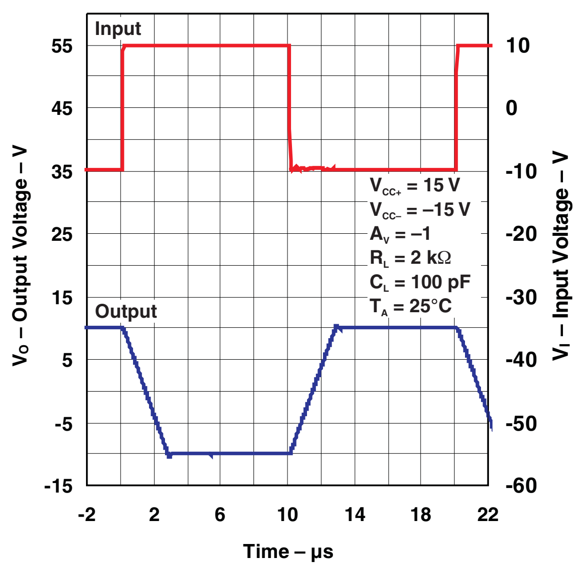

**GAIN AND PHASE MARGIN vs DIFFERENTIAL SOURCE RESISTANCE**




**LARGE SIGNAL TRANSIENT RESPONSE ($A_V$ = 1)**

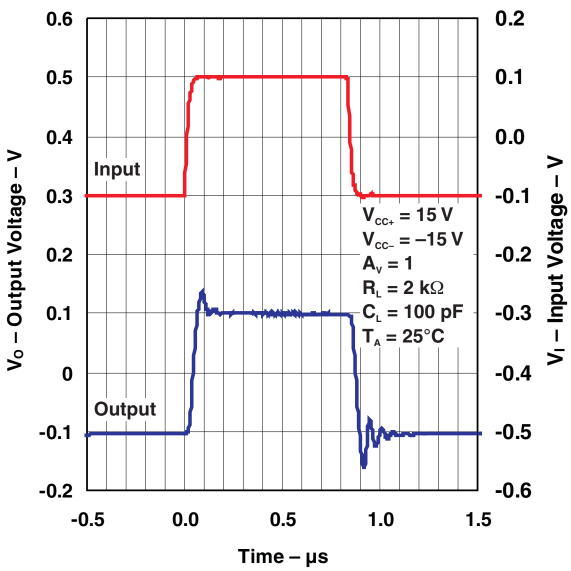



**LARGE SIGNAL TRANSIENT RESPONSE ($A_V$ = –1)**

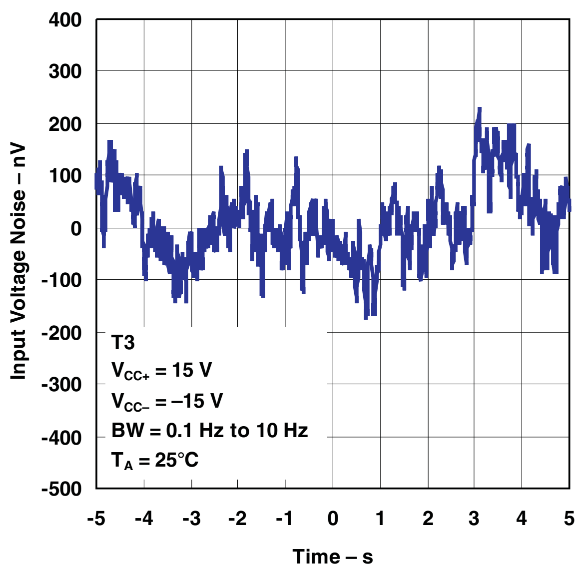


## TYPICAL CHARACTERISTICS (continued)

SMALL SIGNAL TRANSIENT RESPONSE




LOW_FREQUENCY NOISE



## APPLICATION INFORMATION

### Output Characteristics

All operating characteristics are specified with 100-pF load capacitance. The MC33078 can drive higher capacitance loads. However, as the load capacitance increases, the resulting response pole occurs at lower frequencies, causing ringing, peaking, or oscillation. The value of the load capacitance at which oscillation occurs varies from lot to lot. If an application appears to be sensitive to oscillation due to load capacitance, adding a small resistance in series with the load should alleviate the problem (see Figure 2).

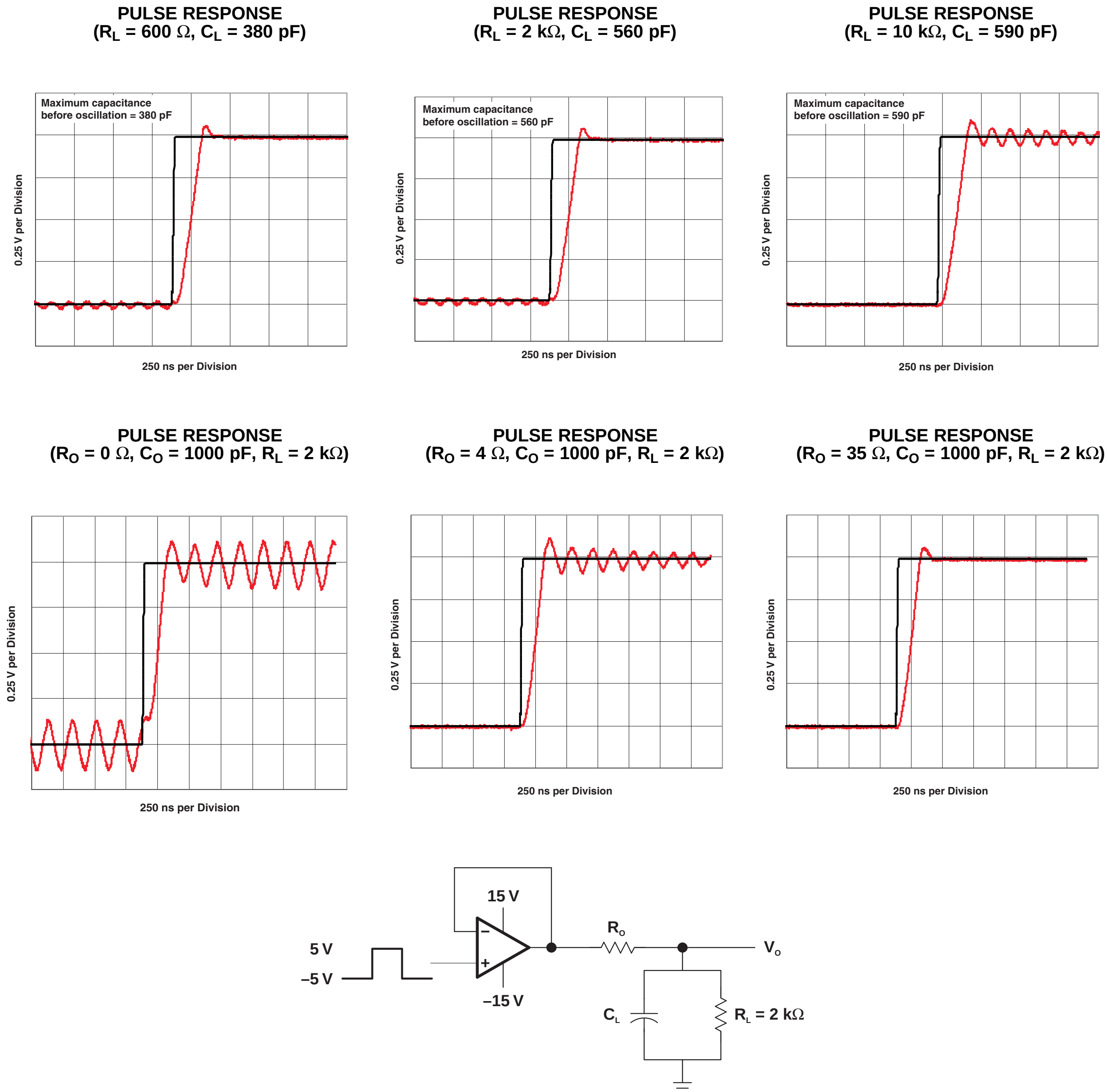



**Figure 2. Output Characteristics**

## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) |
|---|---|---|---|---|---|---|---|---|
| MC33078D | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MC33078DE4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MC33078DG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MC33078DGKR | ACTIVE | MSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MC33078DGKRG4 | ACTIVE | MSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MC33078DGKT | ACTIVE | MSOP | DGK | 8 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MC33078DGKTG4 | ACTIVE | MSOP | DGK | 8 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MC33078DR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MC33078DRE4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MC33078DRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MC33078P | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| MC33078PE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |

(1) The marketing status values are defined as follows:
**ACTIVE:** Product device recommended for new designs.
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
**TBD:** The Pb-Free/Green conversion plan has not been defined.
**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**OTHER QUALIFIED VERSIONS OF MC33078 :**

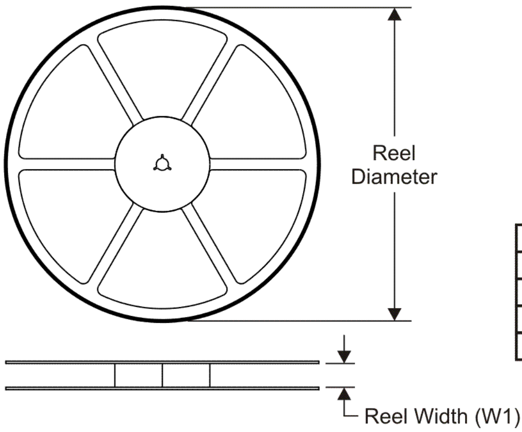
- Enhanced Product: MC33078-EP

NOTE: Qualified Version Definitions:

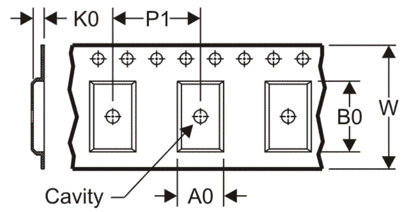
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

## TAPE AND REEL INFORMATION

**REEL DIMENSIONS**

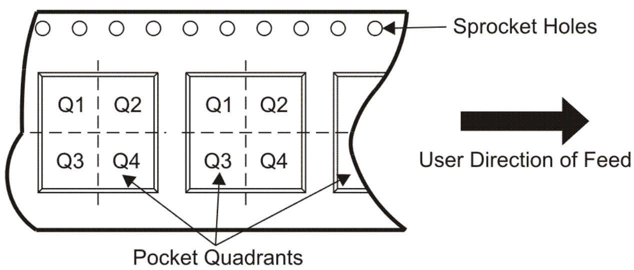



**TAPE DIMENSIONS**




| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

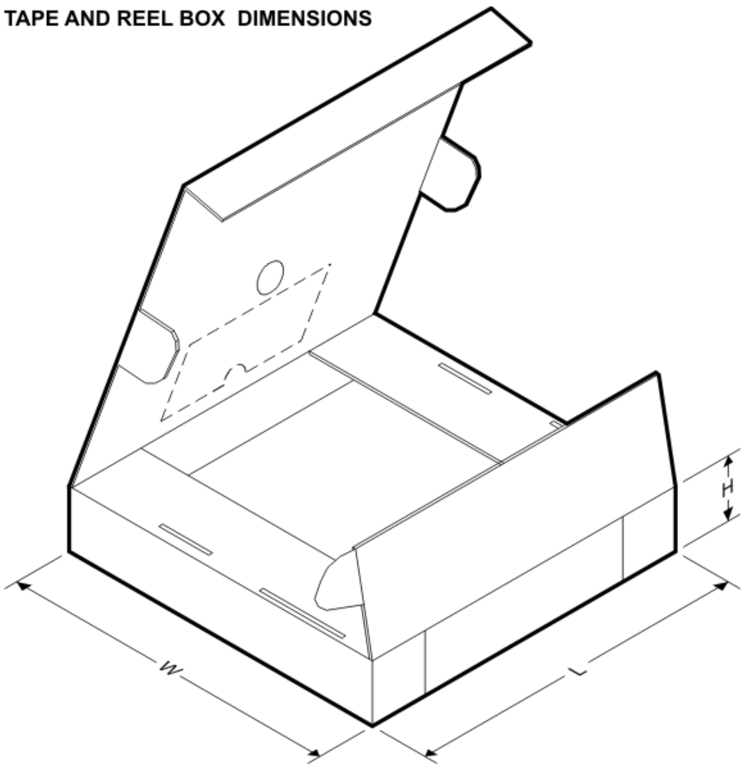
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| MC33078DGKR | MSOP | DGK | 8 | 2500 | 330.0 | 12.4 | 5.3 | 3.3 | 1.3 | 8.0 | 12.0 | Q1 |
| MC33078DGKT | MSOP | DGK | 8 | 250 | 180.0 | 12.4 | 5.3 | 3.3 | 1.3 | 8.0 | 12.0 | Q1 |
| MC33078DR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |

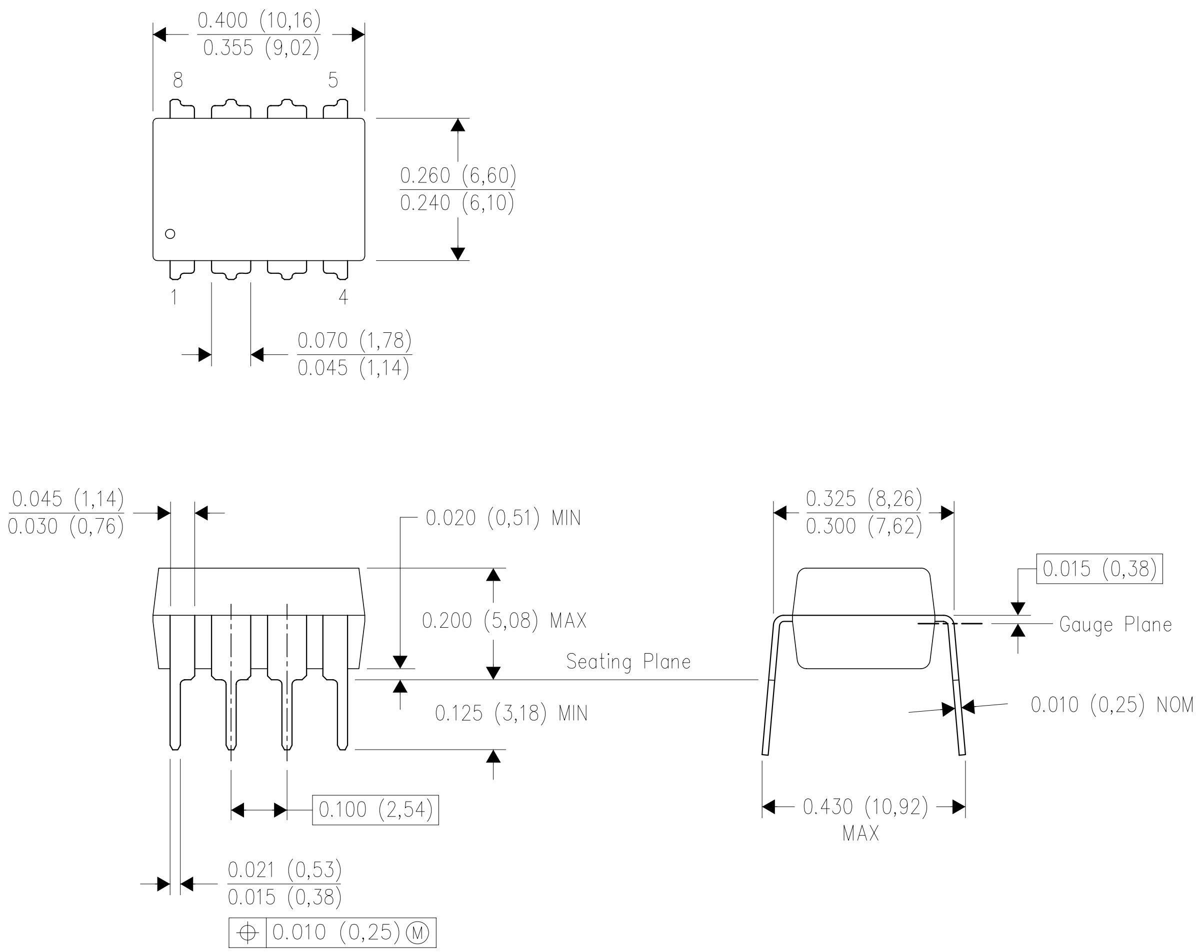
## TAPE AND REEL BOX DIMENSIONS




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| MC33078DGKR | MSOP | DGK | 8 | 2500 | 346.0 | 346.0 | 35.0 |
| MC33078DGKT | MSOP | DGK | 8 | 250 | 220.0 | 205.0 | 50.0 |
| MC33078DR | SOIC | D | 8 | 2500 | 346.0 | 346.0 | 29.0 |

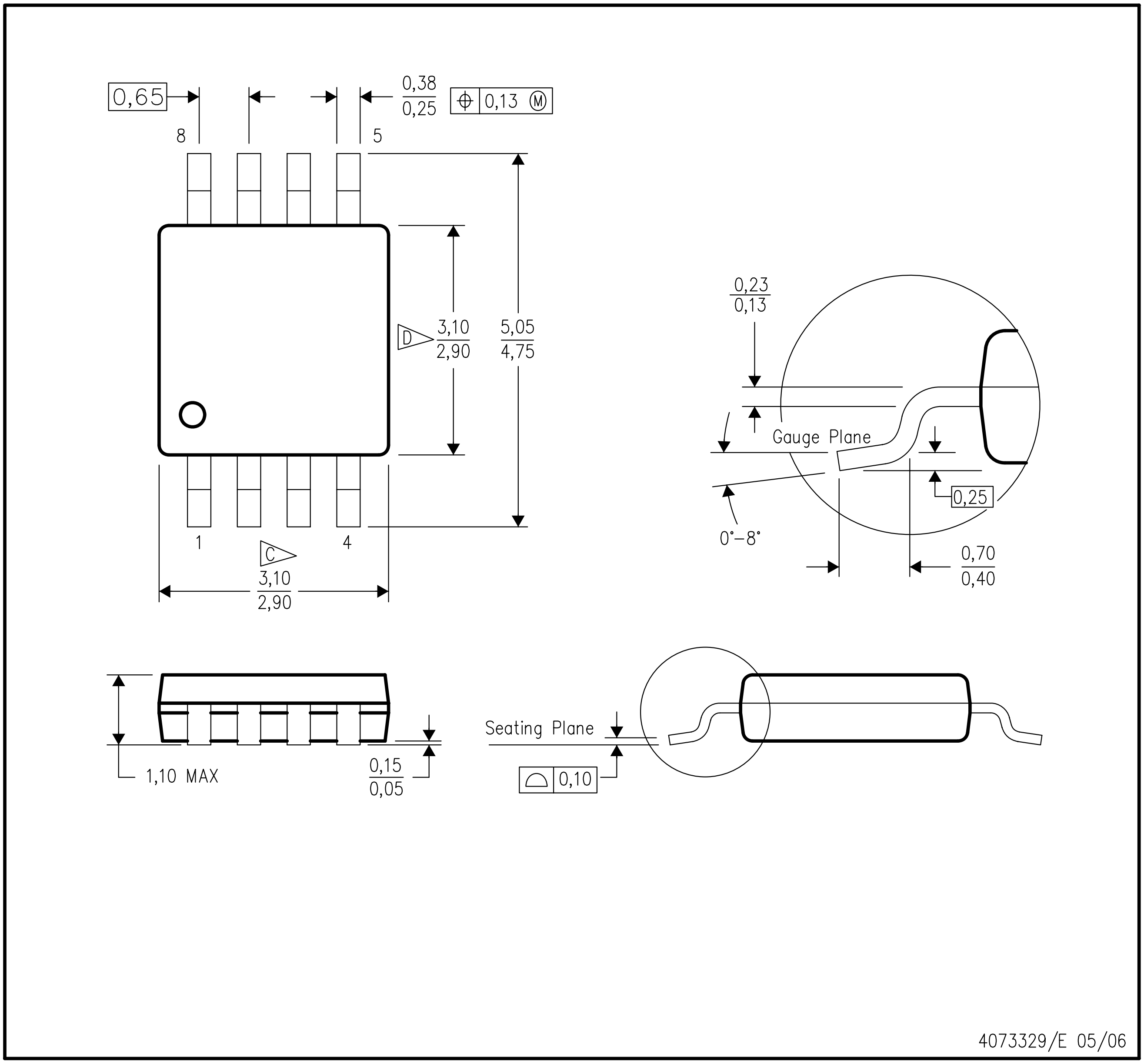
P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE




4040082/E 04/2010

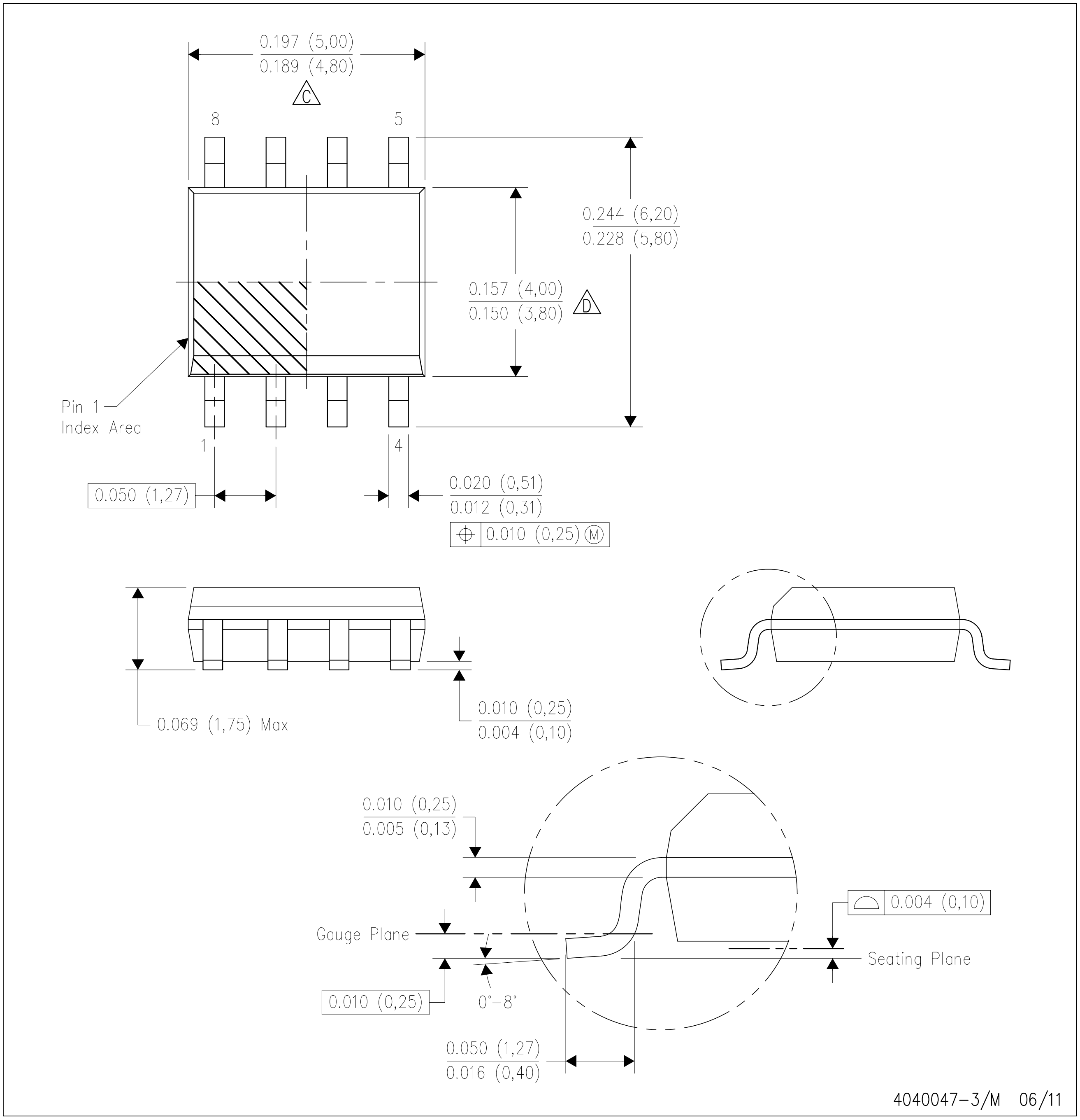
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

DGK (S-PDSO-G8) PLASTIC SMALL-OUTLINE PACKAGE



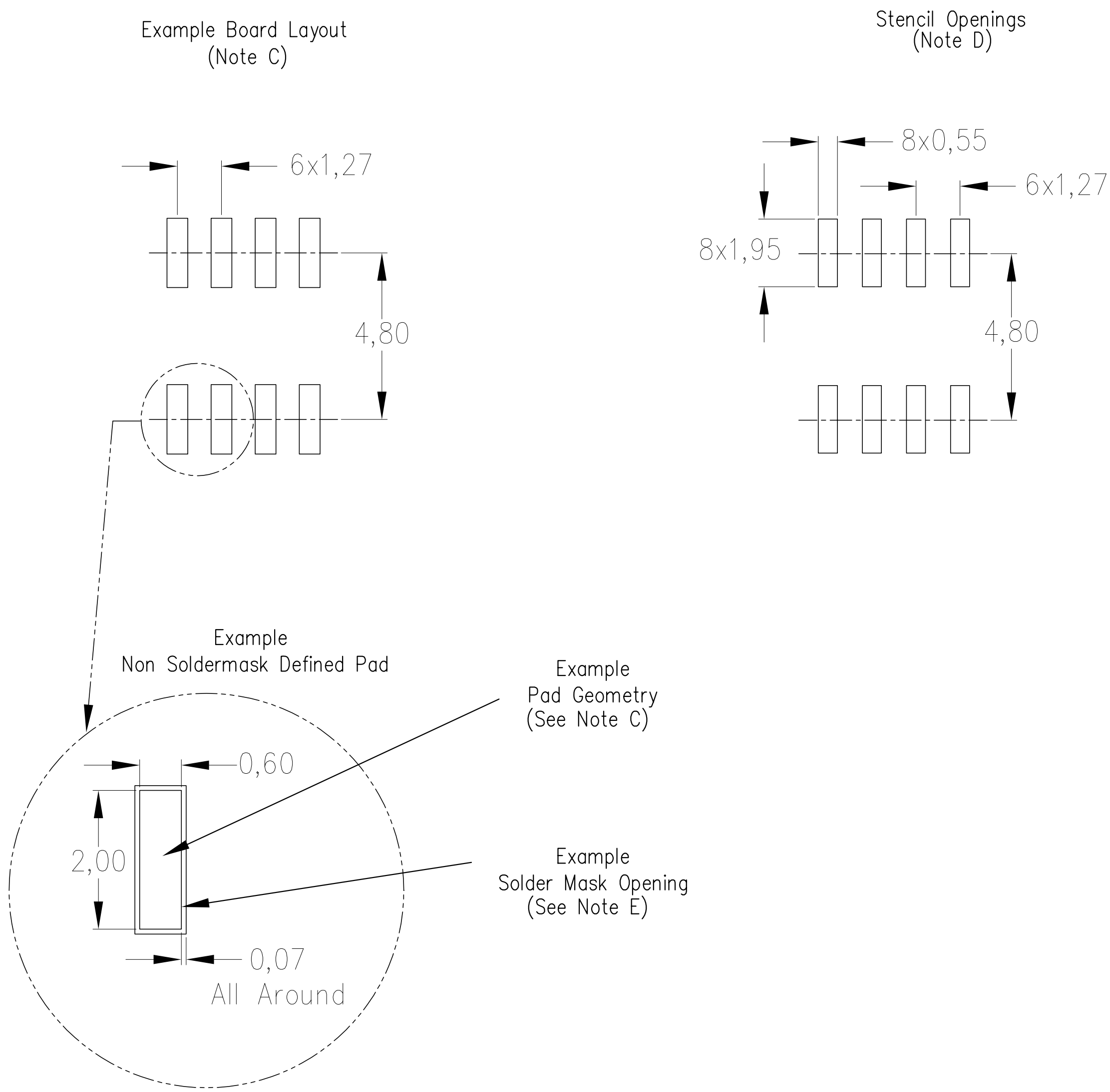

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
E. Falls within JEDEC MO-187 variation AA, except interlead flash.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE




NOTES:
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8) PLASTIC SMALL OUTLINE




4211283-2/D 06/11

NOTES:
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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